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# THE WORLDWIDE IC PACKAGING MARKET

**2008 EDITION**

**The Most Comprehensive Report Available  
On The Global IC Packaging Industry**

## Report Highlights

- **Industry Overview**
  - ◆ **Semiconductor Industry Analysis**
  - ◆ **SATS Company Financial Analysis**
  - ◆ **Global Economic Factors**
- **Worldwide IC Packaging Market Analysis, 2007–2012**
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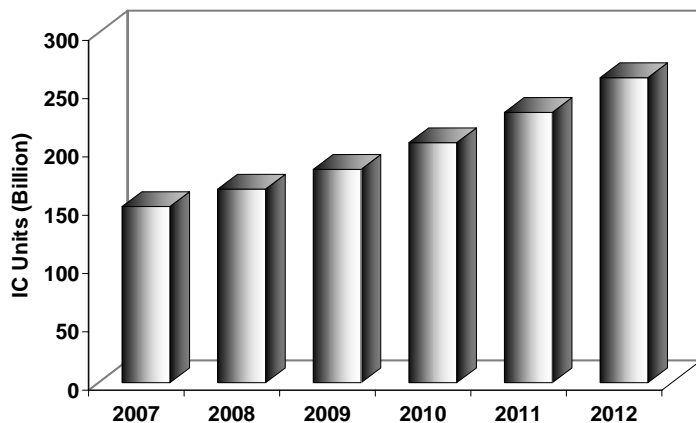
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# The Worldwide IC Packaging Market, 2008 Edition

## Synopsis

Since the end of 2001, annual IC unit shipments have grown an astounding 120 percent. Will this torrid growth continue? If so, what are the implications for the IC packaging industry? *Electronic Trend Publications (ETP)*, in the **2008 Edition of The Worldwide IC Packaging Market**, analyzes the semiconductor industry and uses this analysis to forecast the future of the global IC packaging market.

The report begins with *ETP's* views on the state of the semiconductor industry, along with a top level forecast (see Figure 1).



**Figure 1 IC Unit Forecast**

This discussion includes factors bearing on individual semiconductor products as well as global economic factors. The financial performance of the publicly-traded SATS companies' is a new addition to this discussion.

Following this high-level review, the report presents forecasts for each semiconductor product type, and segments these products by package family and I/O count range. Packaging revenue figures are displayed for each segment, based on prices charged in the contract assembly market. The package families are then rolled up by I/O count and semiconductor product. In doing so, the report generates the total value of the IC packaging industry.

Next, the report presents *ETP's* continuing, extensive coverage of the packaging contractor market. Packaging contractors will continue to assume a larger share of the world's IC packaging business. The report breaks the contractor market down by package families and major product categories, providing units and revenue for each category. To help you further assess this robust group of companies, the report profiles the activities of the world's largest contractors and the packages they offer.

**The Worldwide IC Packaging Market, 2008 Edition** continues *ETP's* leadership position in assessing the status and future of IC packaging. This report will provide you with an effective and economical tool for assessing the future of this market. The report sells for \$2995, with extra copies \$350 each. Each copy includes both a hard-bound version and a single-user PDF on CD-ROM. Corporate licensing is available—contact us for pricing. Order your copies today!

## About the Authors

**Sandra Winkler** is the senior analyst for IC packaging at Electronic Trend Publications (ETP). She began her analyst career as an independent consultant to the telecommunications industry nearly 20 years ago. Since 1995, Ms. Winkler has authored all of ETP's widely cited reports on IC packaging. She has spoken at numerous industry conferences and has written articles for a variety of trade publications. Ms. Winkler has an MBA from Santa Clara University.

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